VISHAY PRECISION GROUP

Ultra Precision SMT Resistor (Wire-Bondable)



EP, EQ Series

Alpha Electronics

TCR, RESISTANCE RANGE, TOLERANCE, RATED POWER						
Туре	TCR (ppm/°C) -55°C to +125°C	Resistance Range (Ω)	Resistance Tolerance (%)	Rated Power (W) at 70°C		
EP	0±5 See Fig.1	30 to 100	±0.1	0.1		
		100 to 30k	±0.05	0.1		
EQ		30 to 100	±0.1	0 1 2 5		
		100 to 60k	±0.05	0.125		



Resistance value, in ohm, is expressed by a series of five characters, four of which represent significant digits. R or K is a dual-purpose letter that designates both the value range (R for ohmic; K for kilo-ohm) and the location of the decimal point.









E Alpha Electronics

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PERFORMANCE							
Parameters	Test Condition	MIL-R-55342 Specification	ALPHA Typical Test Data				
Maximum Rated Operating Temperature Working Temperature Range Maximum Working Voltage Maximum Working Current		70°C -65°C to +125°C 40V 350 mA					
Thermal Shock	-65°C/30 min. \leftrightarrow +125°C/30 min., 5 cycles	±0.05%	±0.01%				
Resistance to Bonding Exposure Low Temperature Operation Overload	Room Temperature, 4 hrs. to 12 hrs. -65°C, No Load, 1 hr. \rightarrow Rated Voltage, 45 min. Rated Voltage x 2.5, 5 sec.	±0.05% ±0.05% ±0.05%	±0.01% ±0.01% ±0.01%				
Life	70°C, Rated Power, 1.5 hr. – ON, 0.5 hr. – OFF, 1,000 hrs.	±0.05%	±0.03%				
Moisture Resistance	+65°C to -10°C, 90% RH to 98% RH, No Load, 10 cycles (240 hrs.)	±0.05%	±0.03%				
High Temperature Exposure	125°C, No Load, 100 hrs.	±0.05%	±0.03%				

FIG. 1 EFFECT OF TERMINATION GOLD WIRE ON TCR





PRECAUTION IN USING WIRE-BONDED CHIP RESISTORS

1. Storage

- Storage condition or environment may adversely affect bondability of the terminal pad with wire. Do not store in high temperature and humidity. The recommended storage environment is lower than 40°C, has less than 70% RH humidity and is free from harmful gases such as sulphur and chlorine.
- 2. Caution in Mounting
 - Mounting Method: Die-bonding
 Adhesive for Placement: Thixotropic epoxy (temperature of cure ≤180°C)
 - State of Mounting: shown right
- 3. Recommended Wire Bonding Method
- Bonding Method: Thermosonic ball bonding
- Θ Preheating Temperature: 80°C to 125°C (temperature of the resistors)
 Θ Connecting Wire: dia. 25 μm gold wire
- 4. Protective Coat
 - Avoid direct coating of the resistor with n-methylpyrrolidone

